

01-05-1999

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To the Honorable Commissioner of Patents &



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d original documents or copy thereof.

1. Name of conveying party(ies):

Hocking Chen and Tai-Mo Wang

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: December 15, 1998

Name: TRANSYSTEM, INC.

Internal Address: _____

Street Address: 2F, No. 10, Prosperity
Road II, Hsinchu Science ParkCity: Hsinchu, Taiwan, R. O. C.
State: _____ ZIP: _____Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: December 15, 1998

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Bo-In Lin

Internal Address: _____

Street Address: 13445 Mandoli Drive

City: Los Altos Hills State: CA ZIP: 94022

6. Total number of applications and patents involved: One

7. Total fee (37 CFR 3.41):..... \$ 40.00

☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number: _____

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ching-lu Lin

Name of Person Signing

Signature

Date

Total number of pages comprising cover sheet

Three

Docket No. TRNSYS8702

ASSIGNMENT

INVENTOR
CITY

Whereas, I, Hocking Chen of 2F, No. 10 Prosperity Road II,
Hsinchu Science Park, Hsinchu, Taiwan, ROC
have invented:

TITLE

MECHANICAL STRUCTURE AND METHOD FOR ASSEMBLING AN
ADDRESSABLE MODULE FOR DOWN CONVERTER

DATE INVENTOR
SIGNED THE
DECLARATION

and executed a United States patent application therefor
on Dec. 15. 1998;

Whereas, TRANSSYSTEM, INC., having a place of business at
Hsinchu, Taiwan, Republic of China, (hereinafter called
TransSystem), desires to acquire the entire right, title and interest of
said application and invention, and to any United States and
foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt
whereof is hereby acknowledged, I, the above named, hereby sell,
assign, and transfer to TransSystem, its successors and assigns, the
entire right, title and interest in the said application and
invention therein disclosed for the United States and foreign
countries, and all rights of priority resulting from the filing said
United States application, and I request the Commissioner of
Patents to issue any Letters Patent granted upon the inventions
set forth in said application to TransSystem its successors and
assigns; and I hereby agree that TransSystem may apply for foreign
Letters Patent on said invention and I will execute all papers
necessary in connection with the United States and foreign
applications when called upon to do so by

CITY AND
DATE

Signed and Sealed at Hsinchu, Taiwan, R.O.C.
on Dec. 15 1998.

Hocking Chen

SIGNATURE OF INVENTOR

Docket No. TRNSYS8702

ASSIGNMENT

INVENTOR
CITY

Whereas, I, Tai-Mo Wang of 2F, No. 10 Prosperity Road II,
Hsinchu Science Park, Hsinchu, Taiwan, ROC
have invented:

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United States application, and I request the Commissioner of
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set forth in said application to TransSystem its successors and
assigns; and I hereby agree that TransSystem may apply for foreign
Letters Patent on said invention and I will execute all papers
necessary in connection with the United States and foreign
applications when called upon to do so by

CITY AND
DATE

Signed and Sealed at Hsinchu, Taiwan, ROC
on Dec. 15, 1998.

Tai Mo Wang
SIGNATURE OF INVENTOR